

MM74HC151 8-Channel Digital Multiplexer

General Description

The MM74HC151 high speed Digital multiplexer utilizes advanced silicon-gate CMOS technology. Along with the high noise immunity and low power dissipation of standard CMOS integrated circuits, it possesses the ability to drive 10 LS-TTL loads. The MM74HC151 selects one of the 8 data sources, depending on the address presented on the A, B, and C inputs. It features both true (Y) and complement (W) outputs. The STROBE input must be at a low logic level to enable this multiplexer. A high logic level at the STROBE forces the W output HIGH and the Y output LOW.

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

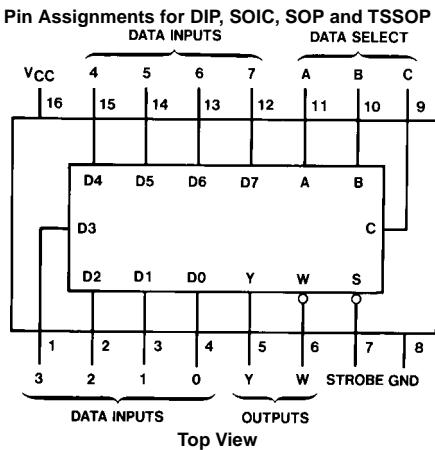
- Typical propagation delay data select to output Y: 26 ns
- Wide operating supply voltage range: 2–6V
- Low input current: 1 μ A maximum
- Low quiescent supply current: 80 μ A maximum (74HC)
- High output drive current: 4 mA minimum

Ordering Code:

Order Number	Package Number	Package Description
MM74HC151M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC151SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC151MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC151N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram

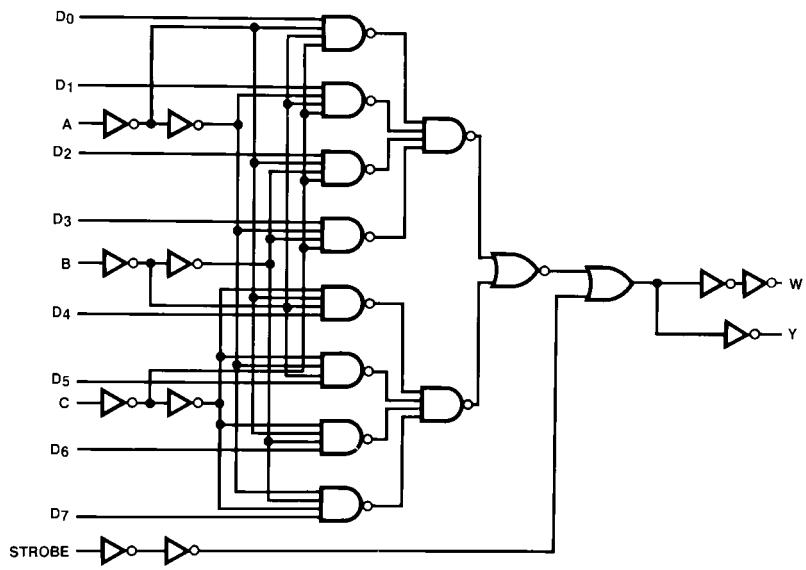


Truth Table

Inputs			Outputs	
Select			Strobe	
C	B	A	S	Y W
X	X	X	H	L H
L	L	L	L	D0 $\overline{D0}$
L	L	H	L	D1 $\overline{D1}$
L	H	L	L	D2 $\overline{D2}$
L	H	H	L	D3 $\overline{D3}$
H	L	L	L	D4 $\overline{D4}$
H	L	H	L	D5 $\overline{D5}$
H	H	L	L	D6 $\overline{D6}$
H	H	H	L	D7 $\overline{D7}$

H = HIGH Level, L = LOW Level, X = Don't Care
D0, D1...D7 = the level of the respective D input

Logic Diagram



Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V_{CC})	-0.5 to +7.0V
DC Input Voltage (V_{IN})	-1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	-0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Power Dissipation (P_D) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L) (Soldering 10 seconds)	260°C

Recommended Operating Conditions

		Min	Max	Units
Supply Voltage (V_{CC})	2	6	V	
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V	
Operating Temperature Range (T_A)	-40	+85	°C	
Input Rise or Fall Times (t_r, t_f)	$V_{CC} = 2.0V$ $V_{CC} = 4.5V$ $V_{CC} = 6.0V$	1000 500 400	ns	

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.**Note 2:** Unless otherwise specified all voltages are referenced to ground.**Note 3:** Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C.**DC Electrical Characteristics** (Note 4)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^\circ C$		$T_A = -40 \text{ to } 85^\circ C$	$T_A = -55 \text{ to } 125^\circ C$	Units
				Typ	Guaranteed Limits			
V_{IH}	Minimum HIGH Level Input Voltage		2.0V	1.5	1.5	1.5	1.5	V
			4.5V	3.15	3.15	3.15	3.15	V
			6.0V	4.2	4.2	4.2	4.2	V
V_{IL}	Maximum LOW Level Input Voltage		2.0V	0.5	0.5	0.5	0.5	V
			4.5V	1.35	1.35	1.35	1.35	V
			6.0V	1.8	1.8	1.8	1.8	V
V_{OH}	Minimum HIGH Level Output Voltage $V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 20 \mu A$		2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 4.0 \text{ mA}$ $ I_{OUT} \leq 5.2 \text{ mA}$		6.0V	6.0	5.9	5.9	5.9	V
			4.5V	4.2	3.98	3.84	3.7	V
V_{OL}	Maximum LOW Level Output Voltage $V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 20 \mu A$		6.0V	5.7	5.48	5.34	5.2	V
			2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 4.0 \text{ mA}$ $ I_{OUT} \leq 5.2 \text{ mA}$		6.0V	0	0.1	0.1	0.1	V
			4.5V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	µA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		8.0	80	160	µA

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

$V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 15 \text{ pF}$, $t_r = t_f = 6 \text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to Y		26	35	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to W		27	35	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Any D to Y		22	29	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay any D to W		24	32	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to Y		17	23	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to W		16	21	ns

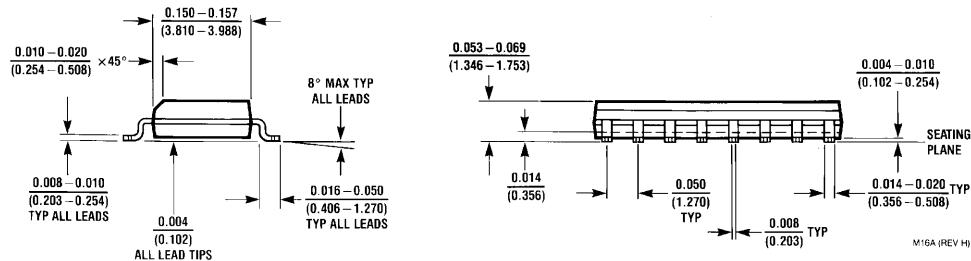
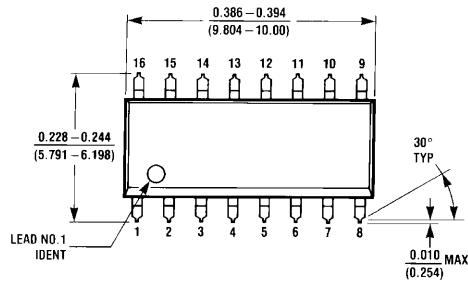
AC Electrical Characteristics

$C_L = 50 \text{ pF}$, $t_r = t_f = 6 \text{ ns}$ (unless otherwise specified)

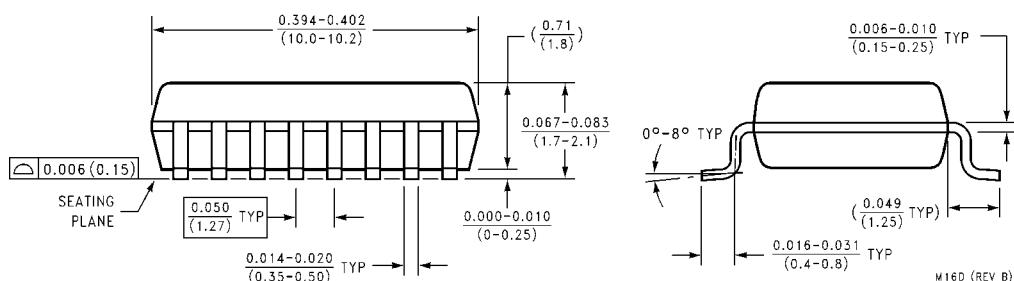
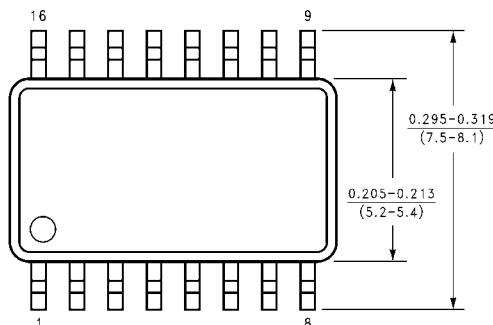
Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^\circ C$			Guaranteed Limits	Units
				Typ	$T_A = -40 \text{ to } 85^\circ C$	$T_A = -55 \text{ to } 125^\circ C$		
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to Y		2.0V	90	205	256	300	ns
			4.5V	31	41	51	60	ns
			6.0V	26	35	44	51	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay A, B or C to W		2.0V	95	205	256	300	ns
			4.5V	32	41	51	60	ns
			6.0V	27	35	44	51	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay any D to Y		2.0V	70	195	244	283	ns
			4.5V	27	39	49	57	ns
			6.0V	23	33	41	48	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay any D to W		2.0V	75	185	231	268	ns
			4.5V	29	37	46	54	ns
			6.0V	25	32	40	46	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to Y		2.0V	50	140	175	203	ns
			4.5V	21	28	35	41	ns
			6.0V	18	24	30	35	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay Strobe to W		2.0V	45	127	159	185	ns
			4.5V	20	25	32	37	ns
			6.0V	17	22	28	32	ns
t_{TLH}, t_{THL}	Maximum Output Rise and Fall Time		2.0V	30	75	95	110	ns
			4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per package)		110				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption,
 $I_S = C_{PD} V_{CC} f + I_{CC}$.

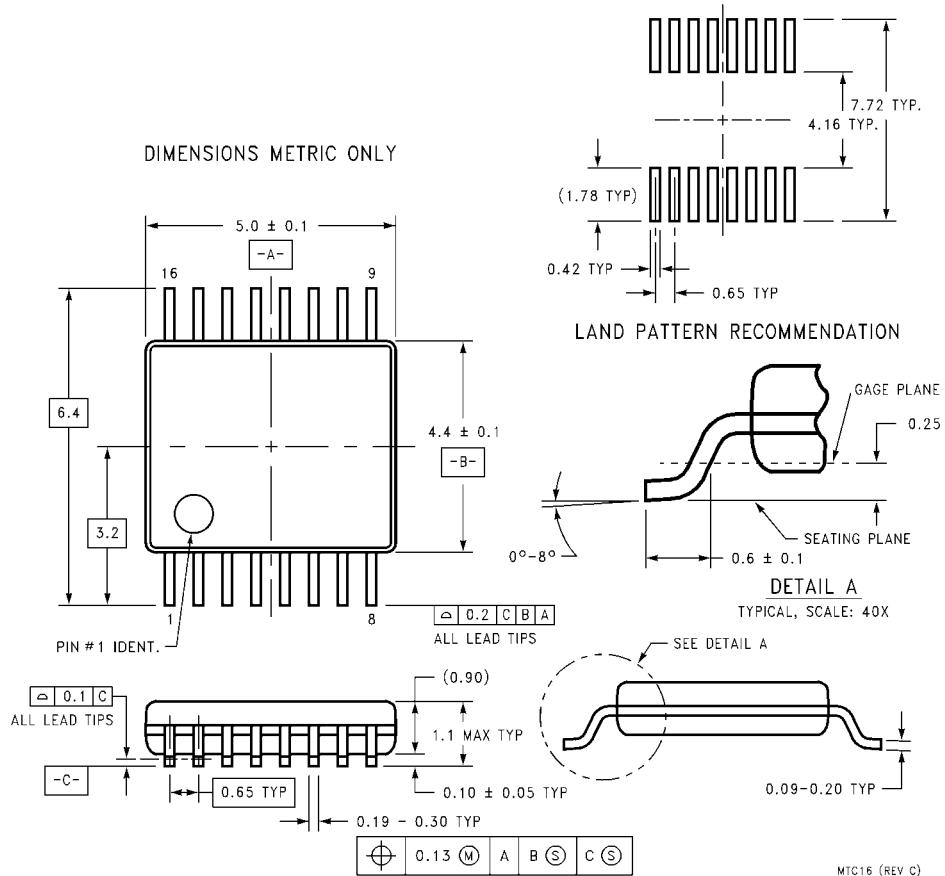
Physical Dimensions inches (millimeters) unless otherwise noted



**16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A**

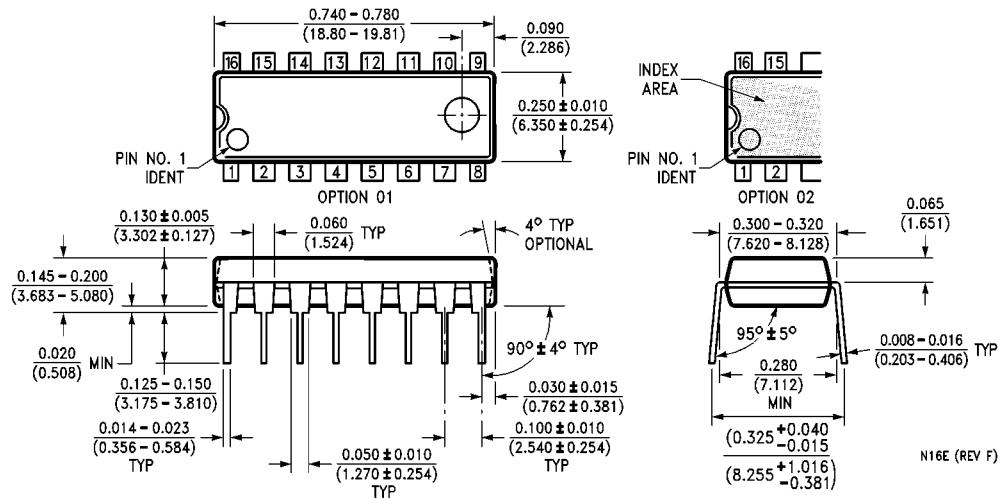


**16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC16

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N16E

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